9805320-0 IPOS COPY + IPER + Annexe

PCT WORLD INTELLECTUAL PROPERTY ORGANIZATION
International Bureau

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification 6 : H01L 21/60 — A1

(11) International Publication Number: WO 97/40530

(43) International Publication Date: 30 October 1997 (30.10.97)

(21) International Application Number: PCT/US97/01145

(22) International Filing Date: 24 January 1997 (24.01.97)

(30) Priority Data:
08/635,111 19 April 1996 (19.04.96) US

(71) Applicant: MOTOROLA INC. [US/US]; 1303 East Algonquin Road, Schaumburg, IL 60196 (US).

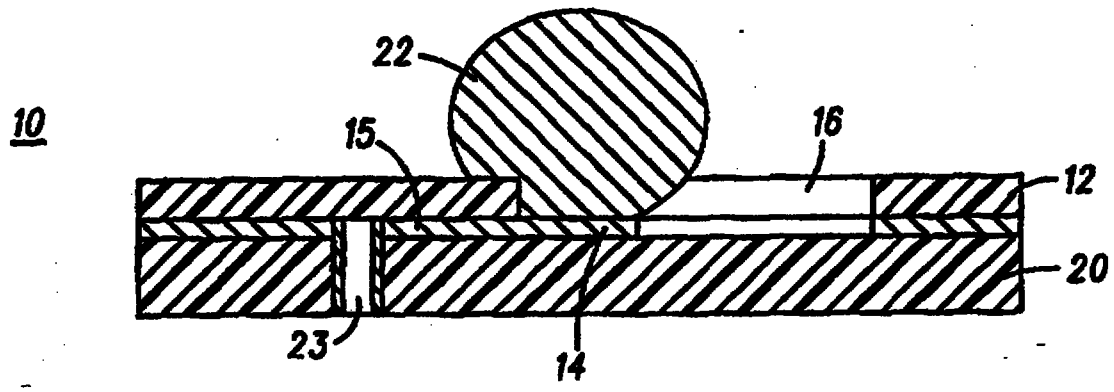
(72) Inventor: MASTERTON, Patrick, J.; 1105 Brighton Drive, Carol Stream, IL 60188 (US).

(74) Agents: CREPS, Heather, L. et al.; Motorola Inc., Intellectual Property Dept., 1303 East Algonquin Road, Schaumburg, IL 60196 (US).

(81) Designated States: JP, KR, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

Published
With international search report.

(54) Title: SOLDER BUMP APPARATUS, ELECTRONIC COMPONENT AND METHOD FOR FORMING A SOLDER BUMP



(57) Abstract

The solder bump apparatus includes a substantially conductive region (14) and a slot (16) projecting from the substantially conductive region (14). A solder resist region (12) at least in part surrounds a perimeter of the substantially conductive region (14) and a perimeter of the slot (16). A solder bump (22) is formed on the conductive region (14) and at least a portion of the solder resist region (12).